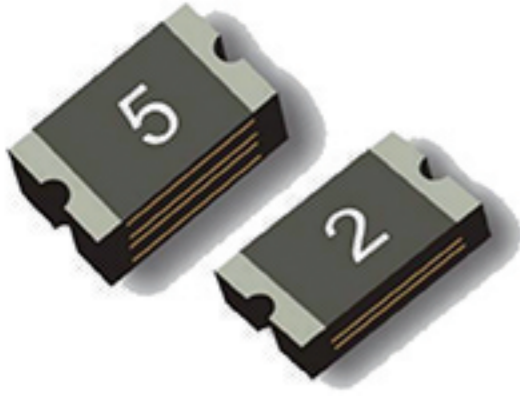


TLC-PSMD Series / PPTC Fuse



Features

- Surface Mount Devices
- Standard 0805mils(2012mm) footprint
- Surface mount packaging for automated assembly
- Compatible with Pb and Pb-free solder reflow profiles.

Applications

- Mobile phones
- PC motherboards
- PDA's/Digital cameras
- USB port protection
- HDMI source protection
- Game console port protection



Electrical Characteristics

P/N	I _H (A)	I _T (A)	V _{max} (V)	I _{max} (A)	Maximum Time to trip		P _d type (w)	Resistance	
					(A)	(Sec.)		R _{min} (Ω)	R1 _{maxn} (Ω)
TLC-PSMD010	0.10	0.30	15.0	100	0.5	1.50	0.50	1.000	7.500
TLC-PSMD010/24	0.10	0.30	24.0	100	0.5	1.50	0.50	1.000	7.500
TLC-PSMD020	0.20	0.50	9.0	100	8.0	0.02	0.50	0.650	3.500
TLC-PSMD035	0.35	0.75	6.0	100	8.0	0.10	0.50	0.250	1.200
TLC-PSMD050	0.50	1.00	6.0	100	8.0	0.10	0.50	0.150	0.900
TLC-PSMD075	0.75	1.50	6.0	100	8.0	0.20	0.60	0.090	0.350
TLC-PSMD100	1.00	2.00	6.0	100	8.0	0.30	0.60	0.060	0.250
TLC-PSMD110	1.10	2.20	6.0	100	8.0	0.30	0.60	0.060	0.210

Note:

I_H: Maximum current at which the device will not trip in 25°C still air.

I_T: Minimum current at which the device will trip in 25°C still air.

V_{max}: Maximum voltage device can withstand without damage at rated current.

I_{max}: Maximum fault current device can withstand without damage at rated voltage.

T_{trip}: Maximum time to trip(s) at assigned current.

P_d typ: Rated working power.

R_{min}: Minimum resistance of device prior to trip at 25°C.

R1_{max}: Maximum resistance of device measured one hour after tripping at 25°C.

Ordering Information

Series	Hold Current	Max. Voltage	Qty
TLC-PSMD			

